

Fig. 1

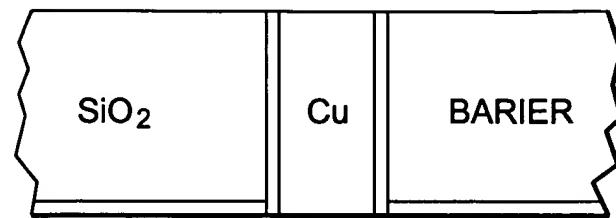


Fig. 2

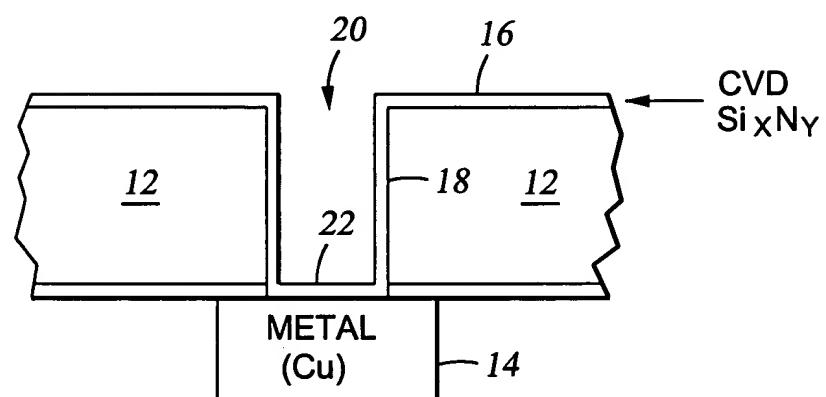


Fig. 3

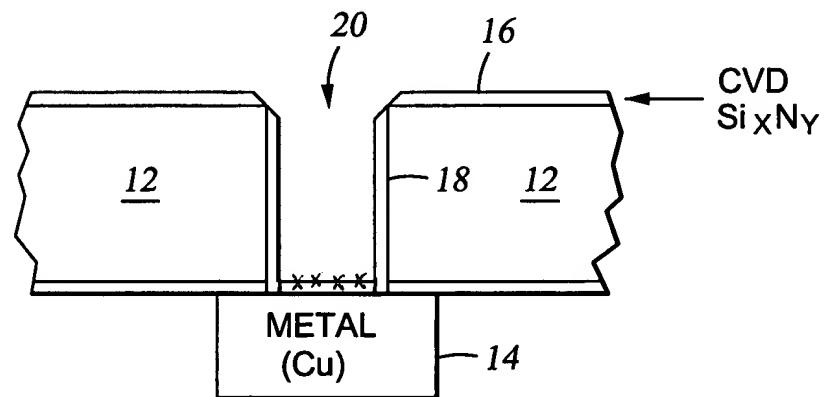


Fig. 4

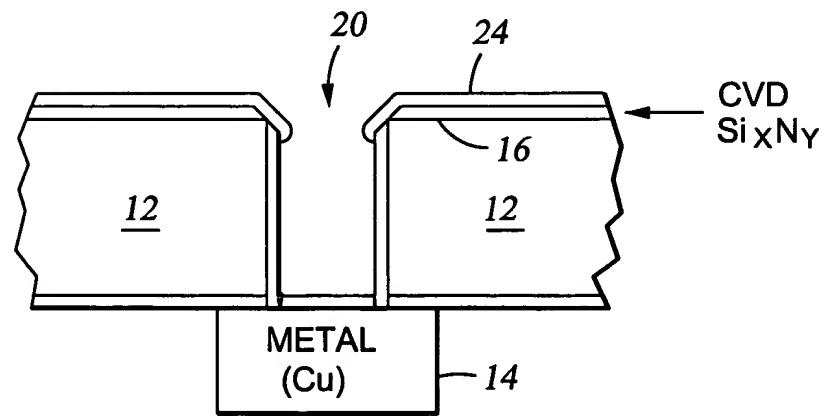


Fig. 5

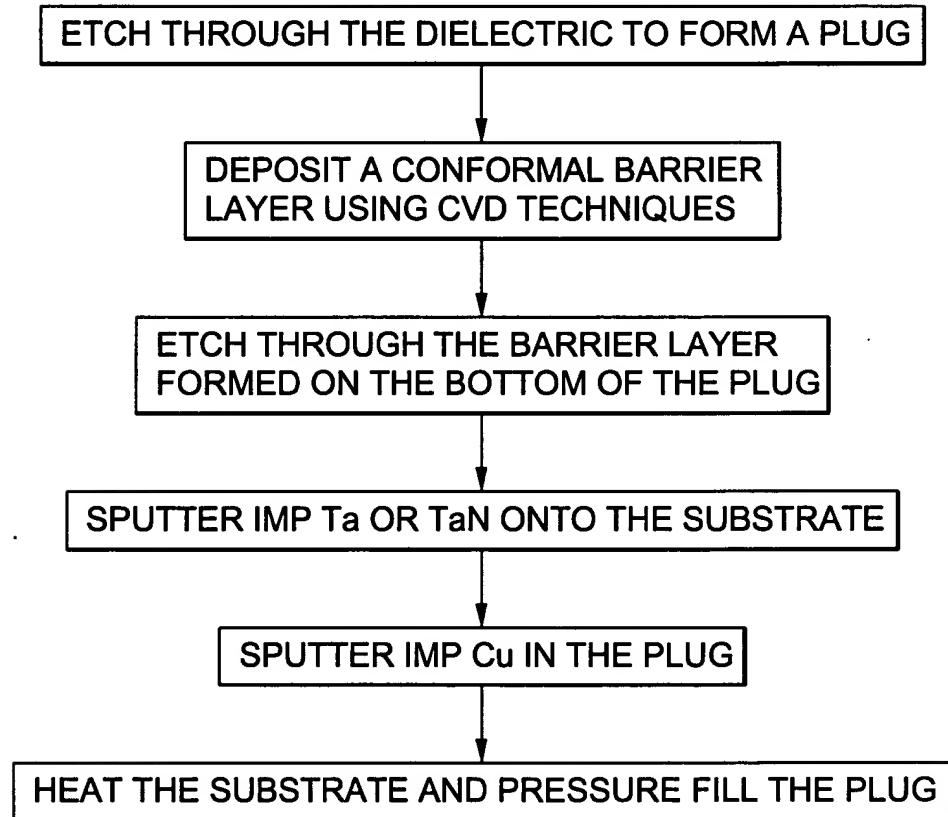
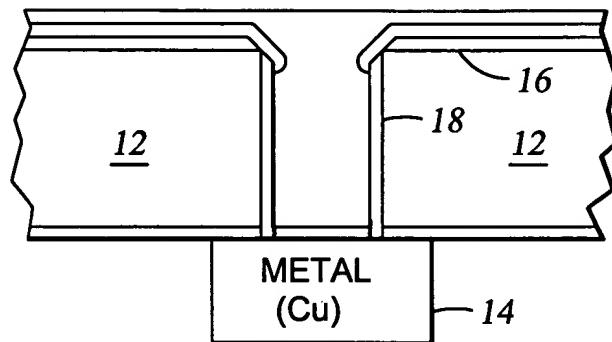


Fig. 6

Fig. 7

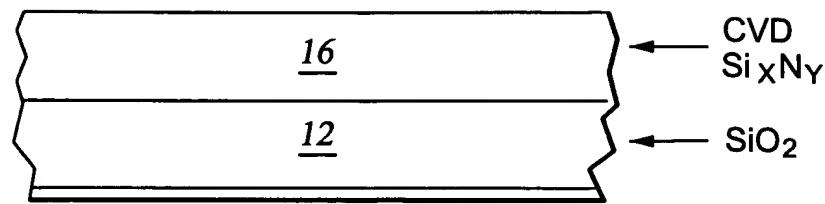


Fig. 8

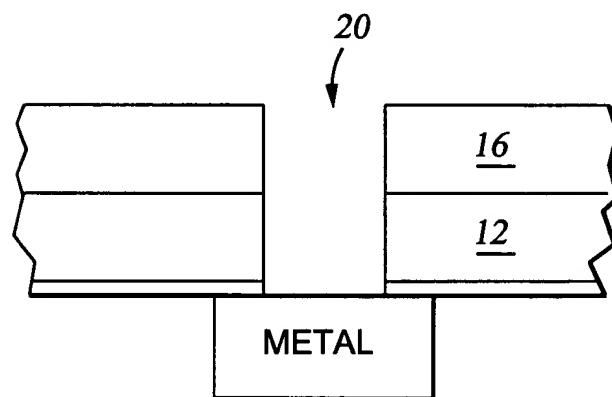


Fig. 9

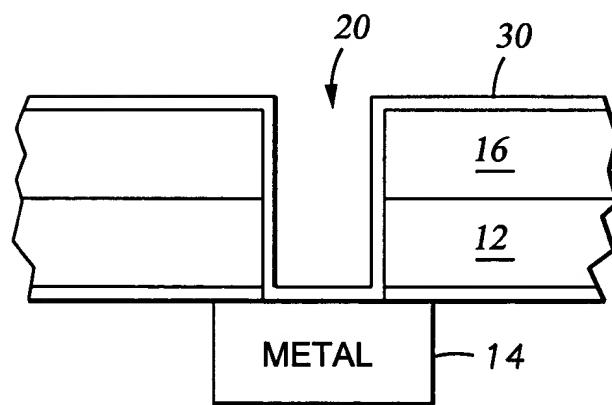


Fig. 10

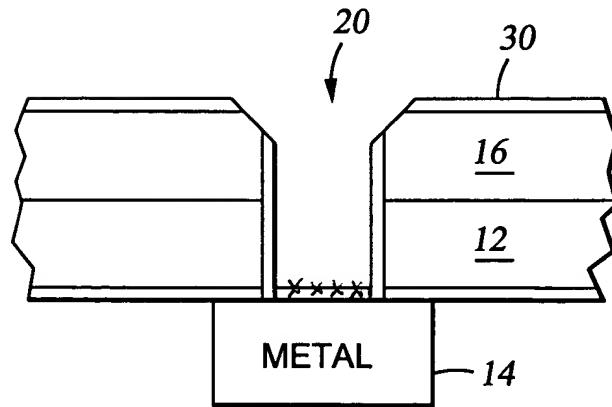


Fig. 11

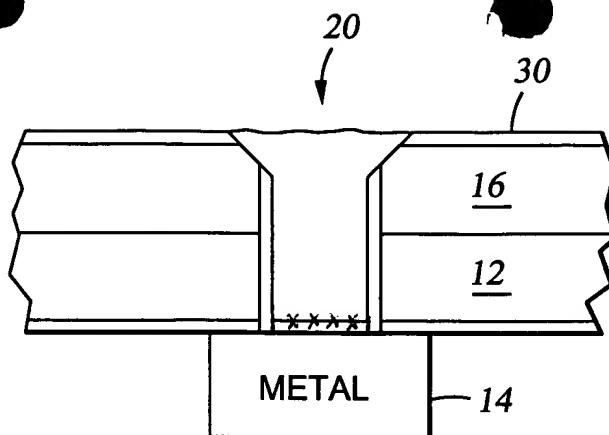
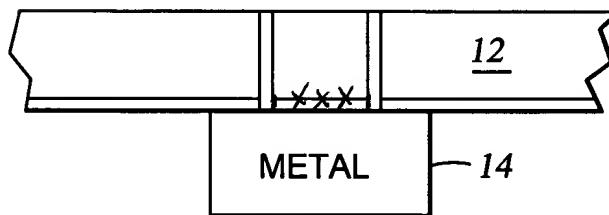


Fig. 12



DEPOSIT A BARRIER LAYER OVER
A BLANKET DIELECTRIC LAYER

PATTERN AND ETCH A PLUG THROUGH THE BARRIER
AND DIELECTRIC LAYER TO THE UNDERLYING FEATURE

DEPOSIT A CONFORMAL BARRIER
LAYER USING CVD TECHNIQUES

ETCH THROUGH THE BARRIER LAYER FORMED
ON THE BOTTOM OF THE PLUG

DEPOSIT Cu SELECTIVELY USING CVD TECHNIQUES

Fig. 13

Fig. 17

